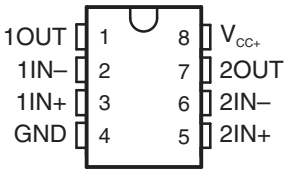
GENERAL-PURPOSE LOW-VOLTAGE COMPARATORS

Check for Samples: LMV331-Q1 SINGLE, LMV393-Q1 DUAL

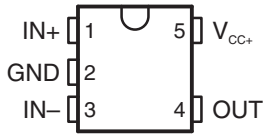
FEATURES

- **Qualified for Automotive Applications**
- **2.7-V and 5-V Performance**
- **Low Supply Current**
  - **LMV331 . . . 60 µA Typ**
  - **LMV393 . . . 100 µA Typ**
- **Input Common-Mode Voltage Range Includes Ground**
- **Low Output Saturation Voltage . . . 200 mV Typ**
- **Open-Collector Output for Maximum Flexibility**

LMV393...D PACKAGE
(TOP VIEW)



LMV331...DBV PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The LMV393-Q1 device is a low-voltage (2.7 V to 5.5 V) version of the dual and quad comparators, LM393 and LM339, which operate from 5 V to 30 V. The LMV331-Q1 is the single-comparator version.

The LMV331-Q1 and LMV393-Q1 are the most cost-effective solutions for applications where low-voltage operation, low power, space saving, and price are the primary specifications in circuit design for portable consumer products. These devices offer specifications that meet or exceed the familiar LM339 and LM393 devices at a fraction of the supply current.

ORDERING INFORMATION(1)

T_A	PACKAGE(2)			ORDERABLE PART NUMBER	TOP-SIDE MARKING(3)
–40°C to 125°C	Single	SOT23-5 – DBV	Reel of 3000	LMV331QDBVRQ1	LADQ
	Dual	SOIC – D	Reel of 2500	LMV393QDRQ1	V393Q1

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
(3) DBV: The actual top-side marking has one additional character that designates the wafer fab/assembly site.

Figure 1. SYMBOL (EACH COMPARATOR)

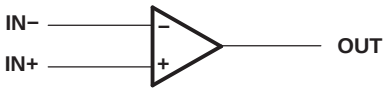
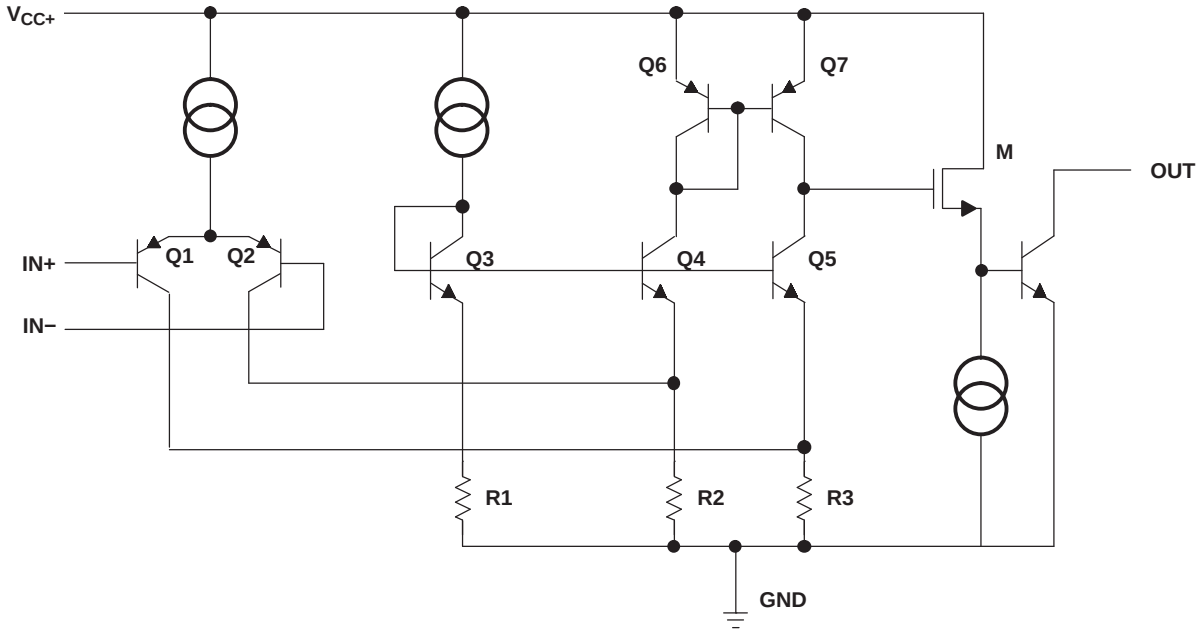


Figure 2. SIMPLIFIED SCHEMATIC



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC+}	Supply voltage(2)			5.5	V
V_{ID}	Differential input voltage(3)			±5.5	V
V_I	Input voltage range (either input)		0	5.5	V
θ_{JA}	Package thermal impedance(4) (5)	D (8-pin) package		97	°C/W
		D (14-pin) package		86	
		DBV package		206	
T_J	Operating virtual junction temperature			150	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values (except differential voltages and V_{CC+} specified for the measurement of I_{OS}) are with respect to the network GND.
(3) Differential voltages are at IN+ with respect to IN–.
(4) Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Selecting the maximum of 150°C can affect reliability.
(5) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions

		MIN	MAX	UNIT
V_{CC+}	Supply voltage (single-supply operation)	2.7	5.5	V
V_{OUT}	Output voltage		V_{CC+} + 0.3	V
T_A	Operating free-air temperature	–40	125	°C

Electrical Characteristics

at specified free-air temperature, V_{CC+} = 2.7 V, GND = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage		25°C		1.7	7	mV
αV_{IO}	Average temperature coefficient of input offset voltage		–40°C to 125°C		5		µV/°C
I_{IB}	Input bias current		25°C		10	250	nA
			–40°C to 125°C			400	
I_{IO}	Input offset current		25°C		5	50	nA
			–40°C to 125°C			150	
I_O	Output current (sinking)	$V_O \leq 1.5$ V	25°C	5	23		mA
	Output leakage current		25°C		0.003		µA
			–40°C to 125°C			1	
V_{ICR}	Common-mode input voltage range		25°C		–0.1 to 2		V
V_{SAT}	Saturation voltage	$I_O \leq 1$ mA	25°C		200		mV
I_{CC}	Supply current	LMV331	25°C		40	100	µA
		LMV393 (both comparators)			70	140	
		LMV339 (all four comparators)			140	200	

Switching Characteristics

T_A = 25°C, V_{CC+} = 2.7 V, R_L = 5.1 kΩ, GND = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
t_{PHL}	Propagation delay, high- to low-level output switching	Input overdrive = 10 mV	1000	ns
		Input overdrive = 100 mV	350	
t_{PLH}	Propagation delay, low- to high-level output switching	Input overdrive = 10 mV	500	ns
		Input overdrive = 100 mV	400	

Electrical Characteristics

at specified free-air temperature, V_{CC+} = 5 V, GND = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage		25°C		1.7	7	mV
			–40°C to 125°C			9	
αV_{IO}	Average temperature coefficient of input offset voltage		25°C		5		µV/°C
I_{IB}	Input bias current		25°C		25	250	nA
			–40°C to 125°C			400	
I_{IO}	Input offset current		25°C		2	50	nA
			–40°C to 125°C			150	
I_O	Output current (sinking)	$V_O \le 1.5$ V	25°C	10	84		mA
	Output leakage current		25°C		0.003		µA
			–40°C to 125°C			1	
V_{ICR}	Common-mode input voltage range		25°C		–0.1 to 4.2		V
A_{VD}	Large-signal differential voltage gain		25°C	20	50		V/mV
V_{SAT}	Saturation voltage	$I_O \le 4$ mA	25°C		200	400	mV
			–40°C to 125°C			700	
I_{CC}	Supply current	LMV331	25°C		60	120	µA
			–40°C to 125°C			150	
		LMV393 (both comparators)	25°C		100	200	
			–40°C to 125°C			250	
		LMV339 (all four comparators)	25°C		170	300	
			–40°C to 125°C			350	

Switching Characteristics

T_A = 25°C, V_{CC+} = 5 V, R_L = 5.1 kΩ, GND = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
t_{PHL}	Propagation delay, high- to low-level output switching	Input overdrive = 10 mV	600	ns
		Input overdrive = 100 mV	200	
t_{PLH}	Propagation delay, low- to high-level output switching	Input overdrive = 10 mV	450	ns
		Input overdrive = 100 mV	300	

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMV331QDBVRQ1	Active	Production	SOT-23 (DBV) | 5	3000 | LARGE T&R	Yes	NIPDAU | NIPDAU	Level-1-260C-UNLIM	-40 to 125	LADQ
LMV331QDBVRQ1.A	Active	Production	SOT-23 (DBV) | 5	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LADQ
LMV331QDBVRQ1.B	Active	Production	SOT-23 (DBV) | 5	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LADQ
LMV393QDRQ1	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V393Q1
LMV393QDRQ1.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V393Q1
LMV393QDRQ1.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V393Q1

(1) Status: For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF LMV331-Q1, LMV393-Q1 :

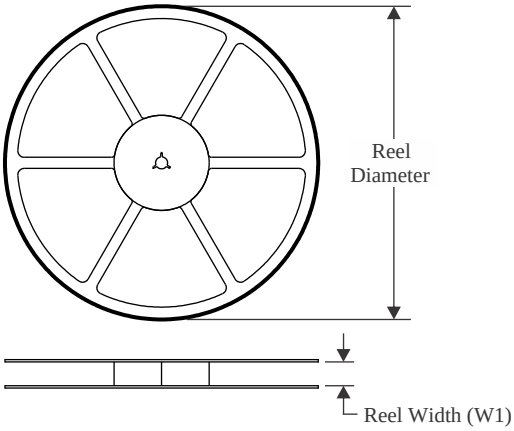
- Catalog : LMV331, LMV393

NOTE: Qualified Version Definitions:

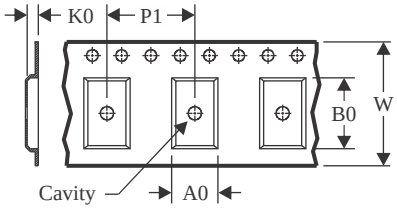
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

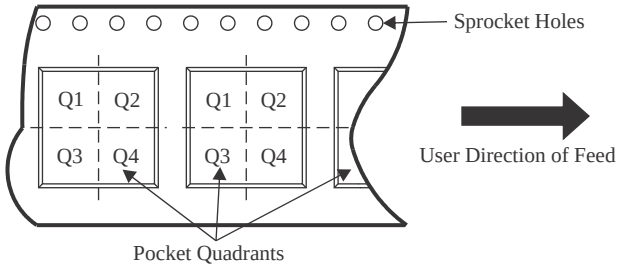


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

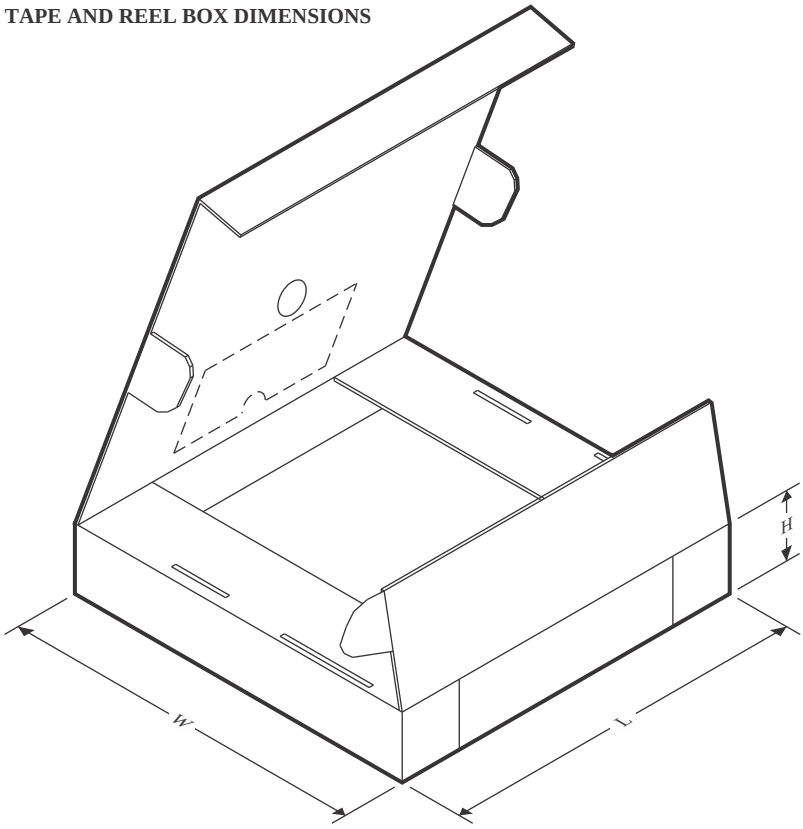
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMV331QDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV331QDBVRQ1	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

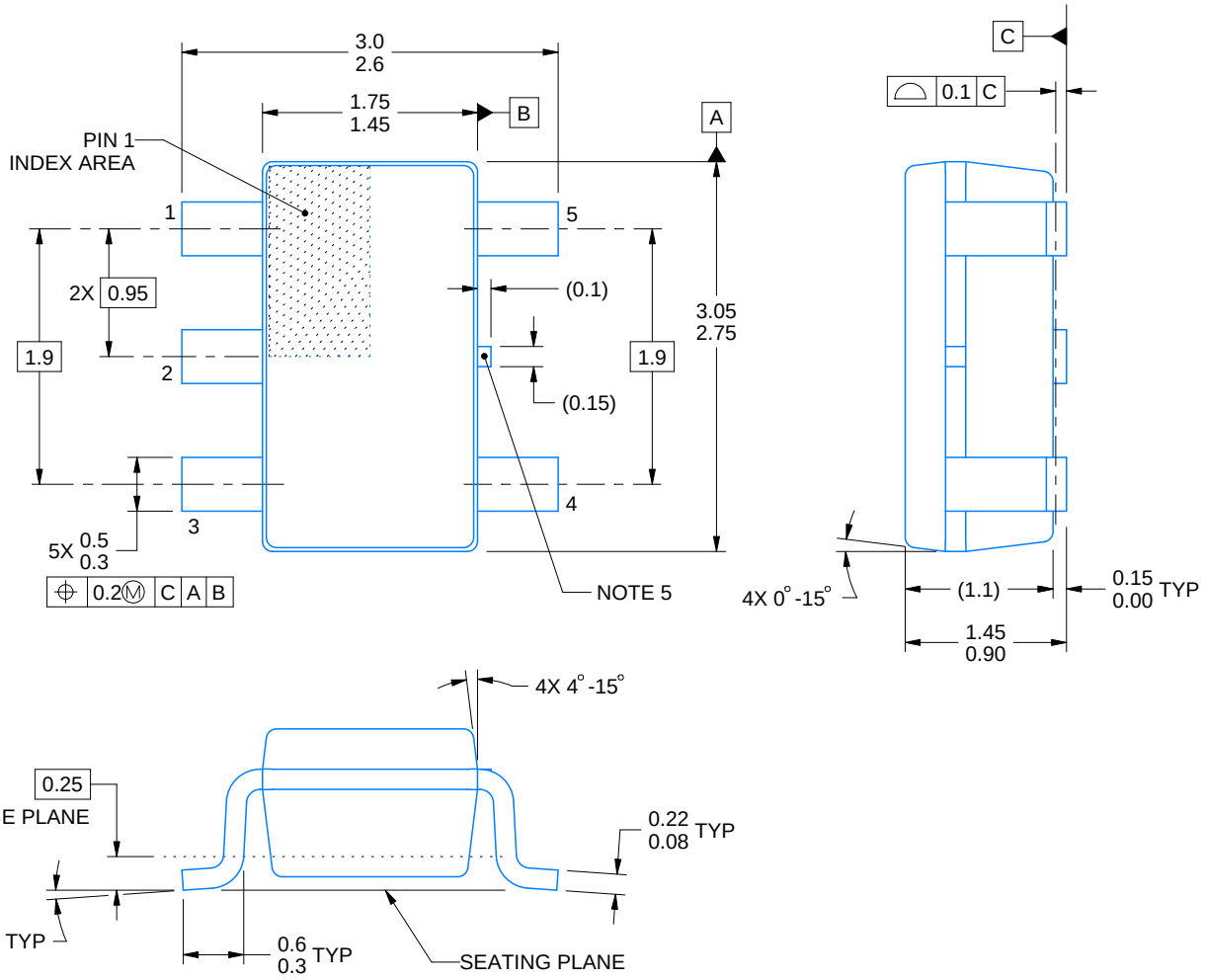
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMV331QDBVRQ1	SOT-23	DBV	5	3000	200.0	183.0	25.0
LMV331QDBVRQ1	SOT-23	DBV	5	3000	210.0	185.0	35.0

PACKAGE OUTLINE

DBV0005A

SOT-23 - 1.45 mm max height

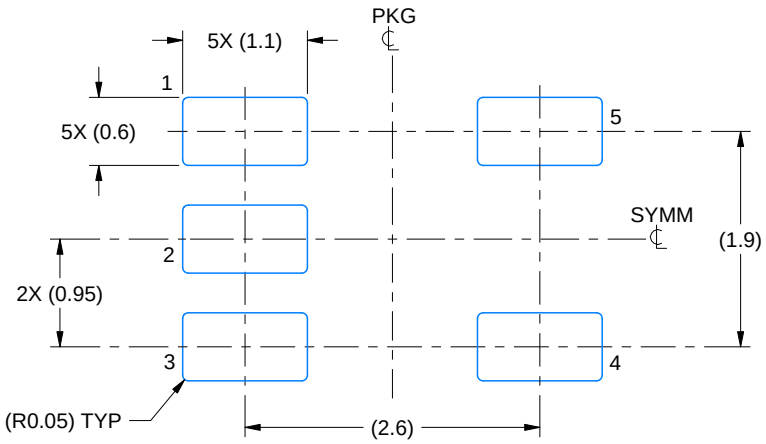
SMALL OUTLINE TRANSISTOR



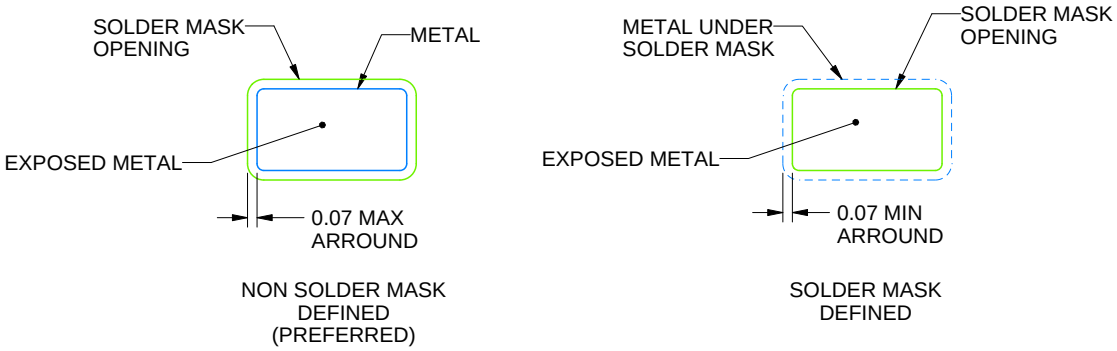
4214839/K 08/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

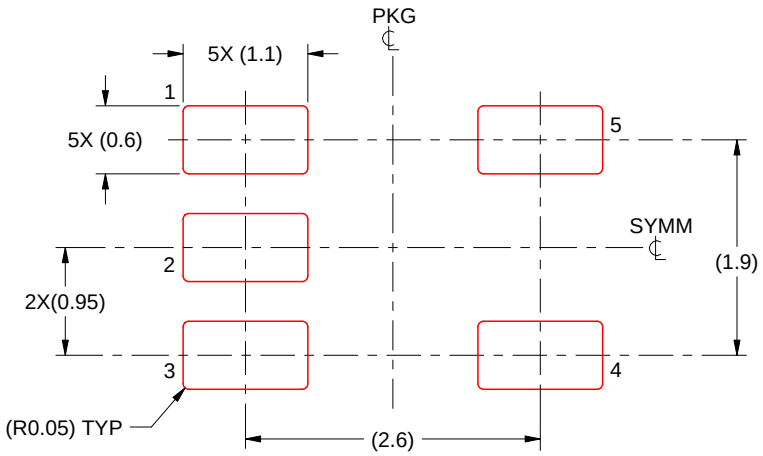


SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

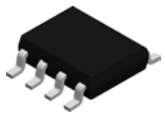


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

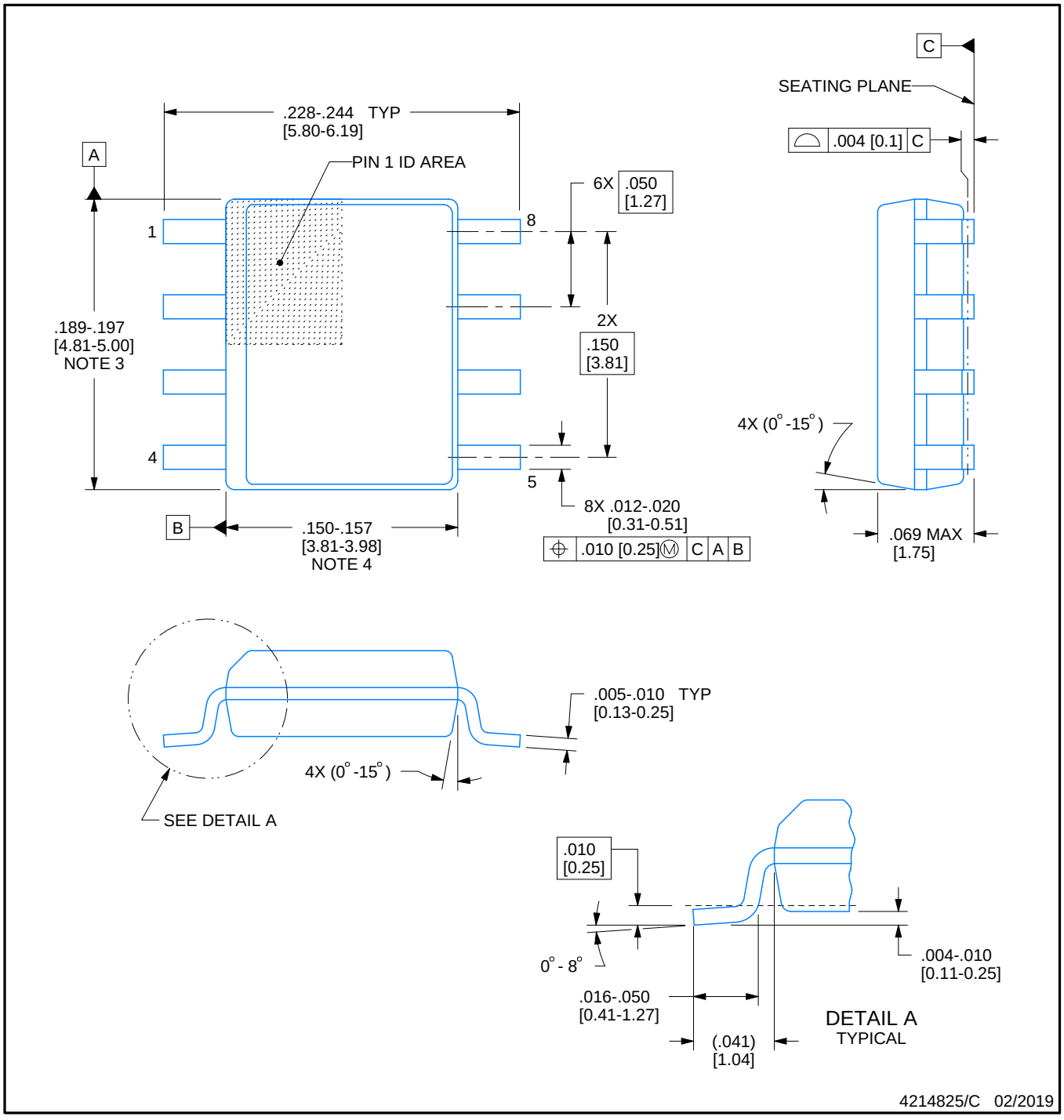


PACKAGE OUTLINE

D0008A

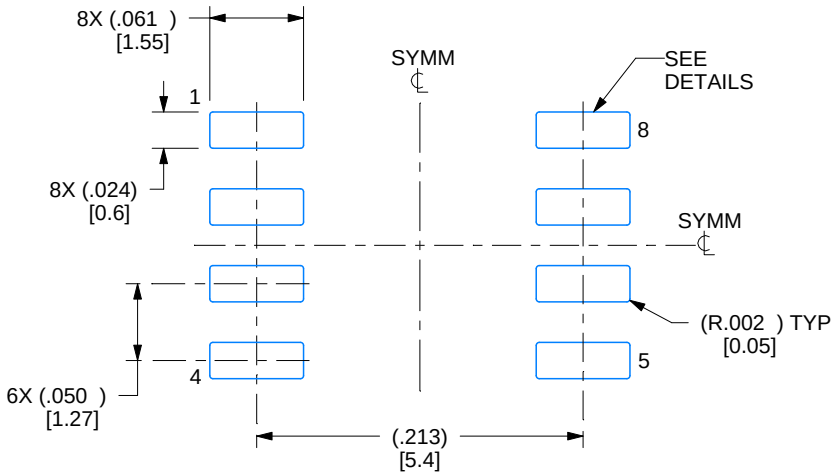
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

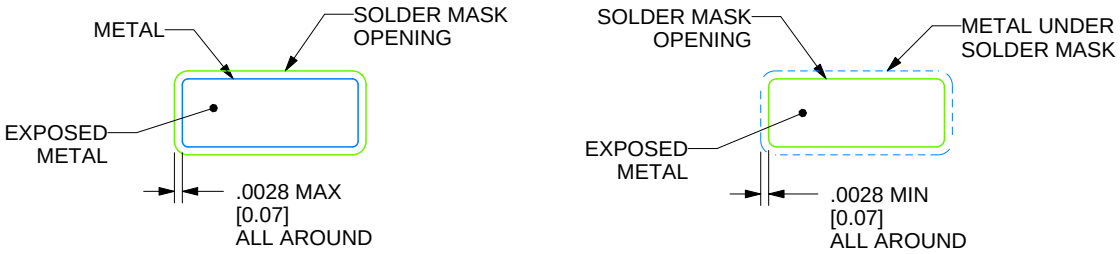


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

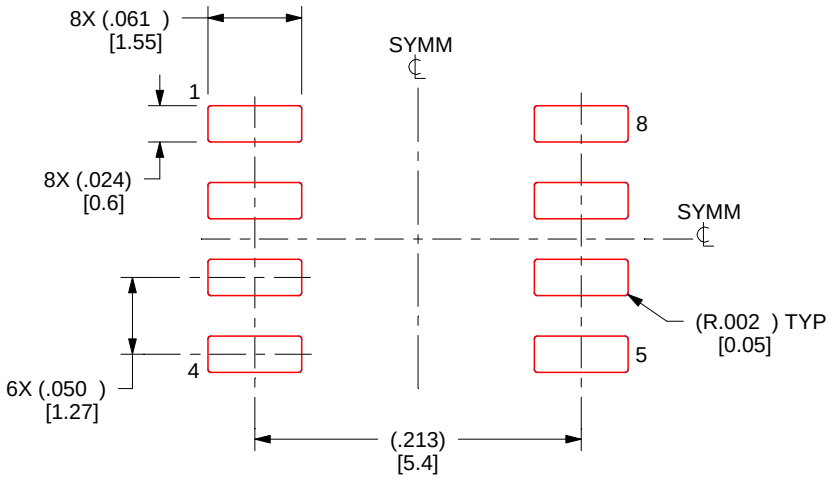
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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